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B2 14. A polyamide composition comprising a polyamide, at least one copper complex and at least one organic halogen compound.

15. A polyamide composition in accordance with Claim 14 wherein said at least one organic halogen compound is selected from the group consisting of an organic chlorine-containing compound, an organic bromine-containing compound and mixtures thereof.

A 16. A polyamide composition in accordance with Claim 14 wherein said at least one copper complex and said at least one halogen compound are present such that the molar ratio of copper to halogen is in the range of between 1:1.5 and 1:15.

17. A polyamide composition in accordance with Claim 16 wherein said at least one copper complex and said at least one halogen compound are present such that the molar ratio of copper to halogen is in the range of between 1:1.5 and 1:15.

18. A polyamide composition in accordance with Claim 14 wherein said at least one copper complex is selected from the group consisting of a complex of copper and a phosphine compound, a complex of copper and a mercaptobenzimidazole compound and a complex of copper, a phosphine compound and a mercaptobenzimidazole compound.

19. A polyamide composition in accordance with Claim 18 wherein said copper complex comprises a halogen-carbon bond.

20. A polyamide composition in accordance with Claim 14 including a compound selected from the group consisting of an organic phosphite, an inorganic phosphonate and an inorganic hypophosphite.

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B2 21. A process of stabilizing a polyamide comprising combining a polyamide with at least one copper complex and at least one organic halogen compound.

22. A process in accordance with Claim 21 wherein said copper complex is selected from the group consisting of a complex of copper and a phosphine compound, a complex of copper and a mercaptobenzamidazole compound and a complex of copper, a phosphine compound and a mercaptobenzamidazole compound.

23. A process in accordance with Claim 22 wherein said copper complex comprises a halogen-carbon bond.

24. A process of preparing a stabilized polyamide composition comprising mixing a polyamide with at least one copper complex and at least one organic halogen compound.

25. A process in accordance with Claim 24 wherein said at least one copper complex and said at least one organic halogen compound are mixed with said polyamide in the form of a masterbatch.

26. A process in accordance wherein said copper complex is selected from the group consisting of a complex of copper and a phosphine compound, a complex of copper and a mercaptobenzamidazole compound and a complex of copper, a phosphine compound and a mercaptobenzamidazole compound.

27. A process in accordance with Claim 25 of adding a compound selected from the group consisting of an organic phosphate, an inorganic phosphonate and an inorganic hypophosphite.

REMARKS

All the claims submitted for examination in this application have been objected to or have been rejected. Applicant has amended his claims and respectfully submits that all the claims currently in this application are patentable over the objections and rejections of record.